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DATA SHEET

PART NO.: L-C195JRLBCT

REV: A / 4

CUSTOMER'S APPROVAL: _____

DCC: _____

DRAWING NO.: DS-78-14-0003

DATE: 2019-5-20

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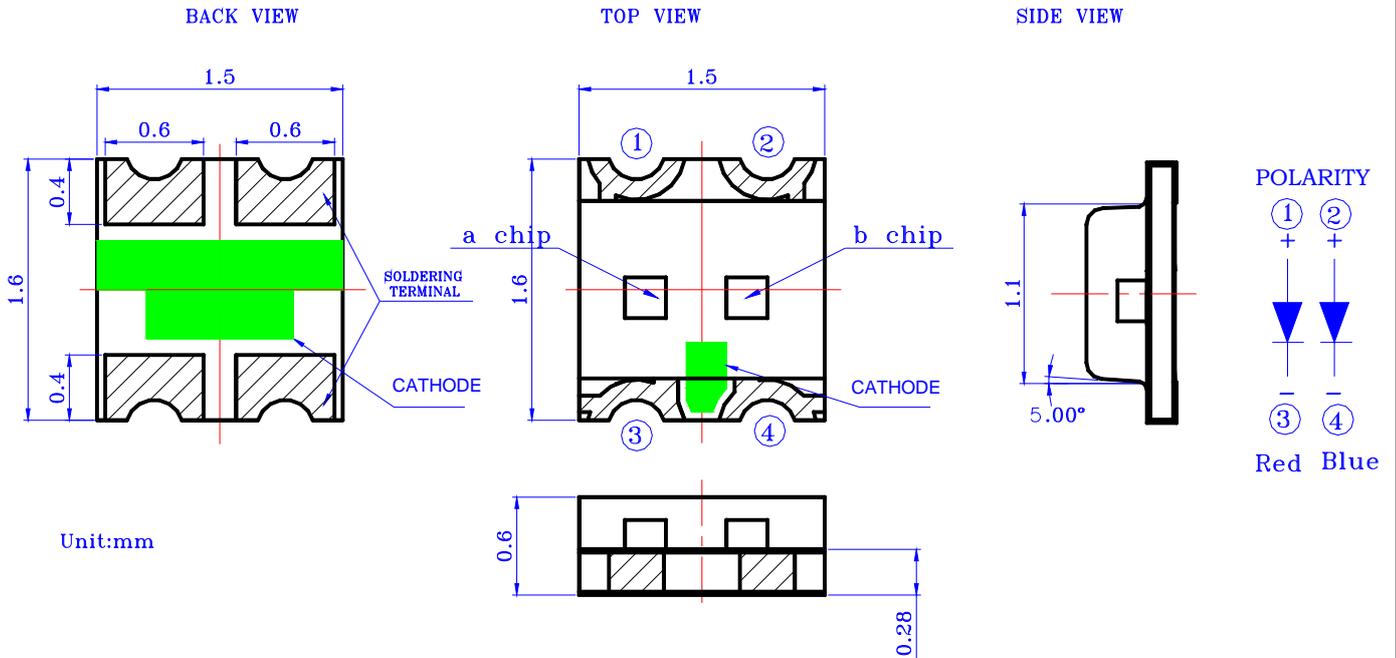


SURFACE MOUNT DEVICE LED

Part No.: L-C195JRLBCT

REV: A / 4

● PACKAGE OUTLINE DIMENSIONS



Notes:

1. a chip: Red; b chip: Blue
2. All dimensions are in millimeters.
3. Tolerance is $\pm 0.1\text{mm}$ (.004") unless otherwise noted.

● Features

- * Dual color, top view, wide view angle Chip LED.
- * Package in 8mm tape on 7" diameter reels.
- * Compatible with automatic Pick & Place equipment.
- * Compatible with Reflow soldering and Wave soldering processes.
- * EIA STD package.
- * I.C. compatible.
- * Pb free product.



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● Chip Materials

Chip	Light Color	Dice Material	Lens Color
a	JR: Red	AllnGap	Water Clear
b	LB: Blue	InGaN	

● Absolute Maximum Ratings (Ta=25°C)

Symbol	Parameter	Rating		Unit
		Blue	Red	
PD	Power Dissipation	100	75	mW
IPF	Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	100	80	mA
IF	Continuous Forward Current	25	30	mA
-	De-rating Linear From 25°C	0.25	0.25	mA/°C
VR	Reverse Voltage	5	5	V
ESD	Electrostatic Discharge Threshold (HBM) ^{Note A}	1000	2000	
Topr	Operating Temperature Range	-40 ~ +85		°C
Tstg	Storage Temperature Range	-40 ~ +85		°C
-	Wave Soldering Condition (Two times Max.)	260 (for 5 seconds)		°C
-	Infrared Soldering Condition (Two times MAX.)	240 (for 10 seconds)		°C

Note A:

HBM: Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

● Electro-Optical Characteristics (Ta=25°C)

Parameter		Symbol	Red	Blue	Unit	Test Condition
Luminous Intensity	Min.	IV	28	71	mcd	IF=20mA
	Typ.		40	140		
	Max.					
Viewing Angle	Typ.	2θ 1/2	130		deg	Note 2
Peak Wavelength	Typ.	λ p	639	468	nm	Measurement @Peak
Dominant Wavelength	Typ.	λ d	631	470	nm	IF=20mA
Spectral Line Half-Width	Typ.	Δ λ	17	25	nm	
Forward Voltage	Typ.	VF	1.9	3.0	V	IF =20mA
	Max.		2.4	3.4		
Reverse Current	Max.	IR	10	50	μ A	VR = 5V



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Notes:

1. Luminous intensity is measured with a light sensor and filter combination that proximates the CIE eye-response curve.
2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
3. The dominant wavelength λ_d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
4. Caution in ESD:
Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.
5. Major standard testing equipment by "Instrument System" Model: CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model: 2400.

● Typical Electro-Optical Characteristics Curves

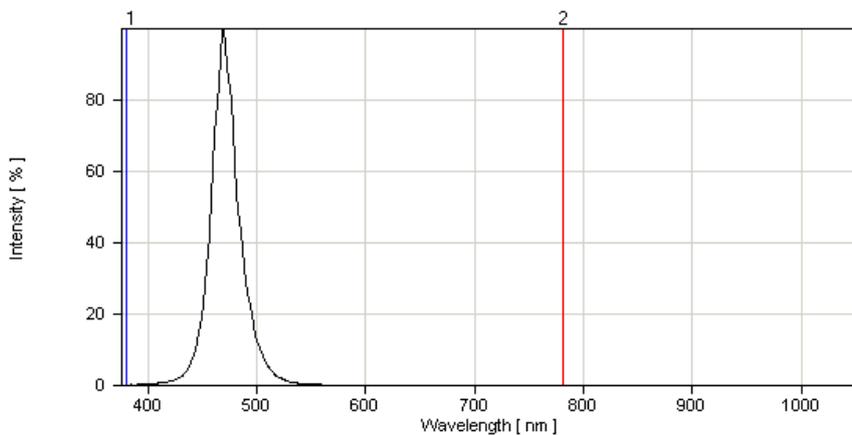


Fig.1 Blue Relative Intensity vs. Wavelength

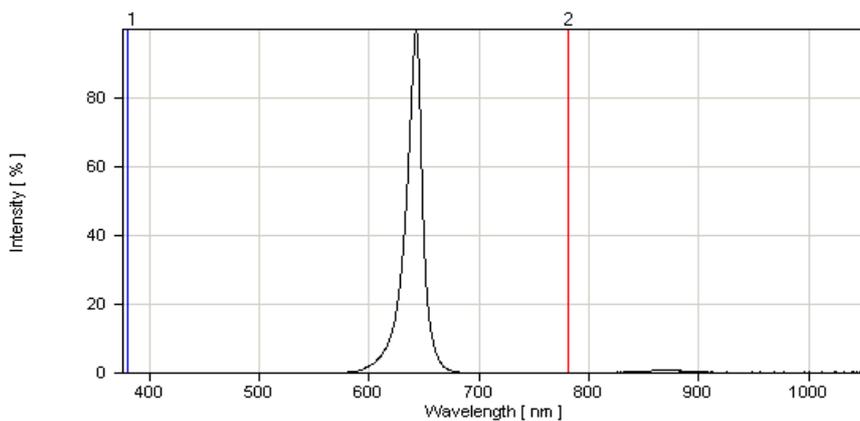


Fig.1 Red Relative Intensity vs. Wavelength



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● Red Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

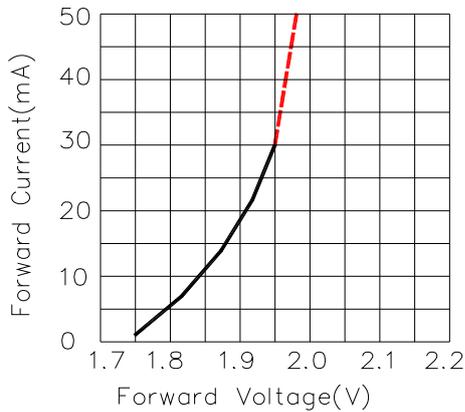


Fig.2 Forward Current vs.Forward Voltage

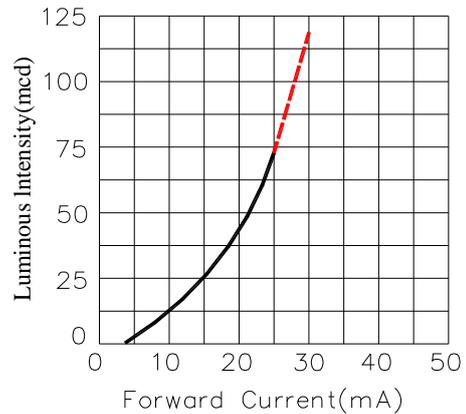


Fig.3 Luminous Intensity vs.Forward Current

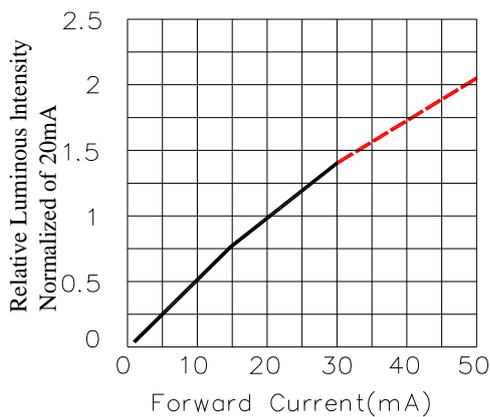


Fig.4 Relative Luminous Intensity vs.Forward Current

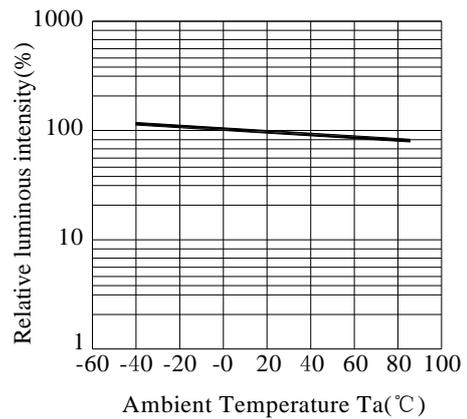


Fig.5 Luminous Intensity vs.Ambient Temperature

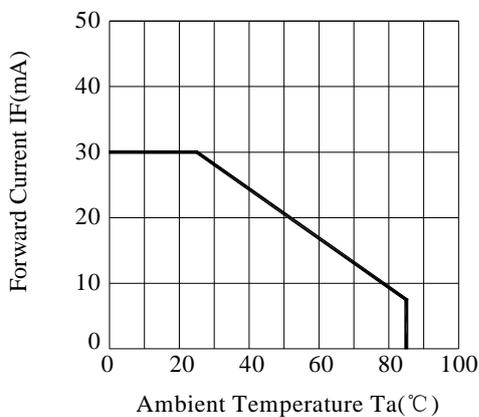


Fig.6 Forward Current Derating Curve

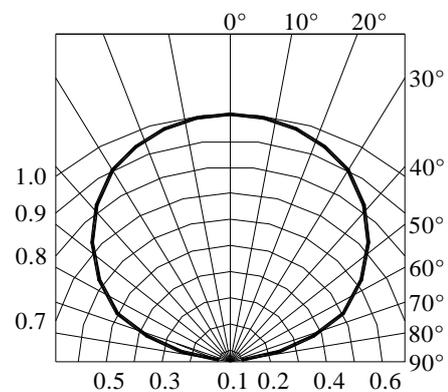


Fig.7 Relative Intensity vs.Angle



SURFACE MOUNT DEVICE LED

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● Blue Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

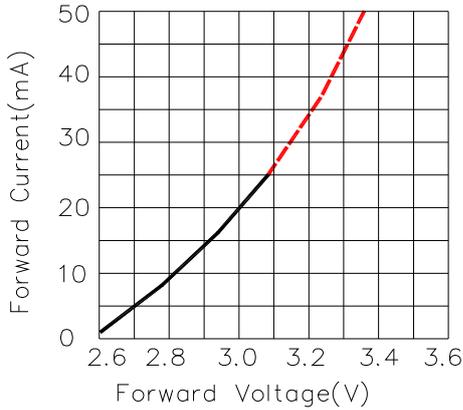


Fig.2 Forward Current vs. Forward Voltage

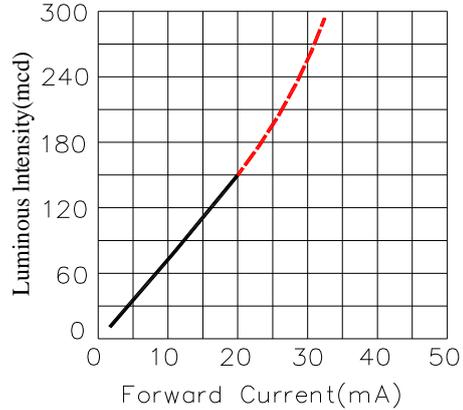


Fig.3 Luminous Intensity vs. Forward Current

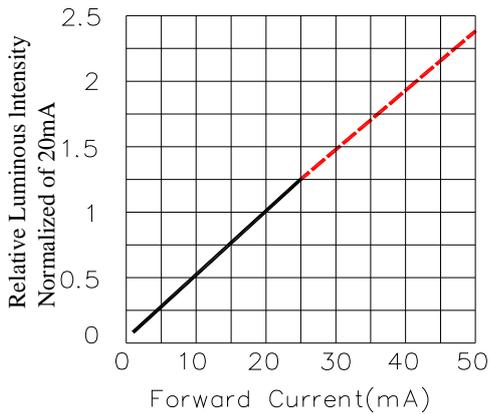


Fig.4 Relative Luminous Intensity vs. Forward Current

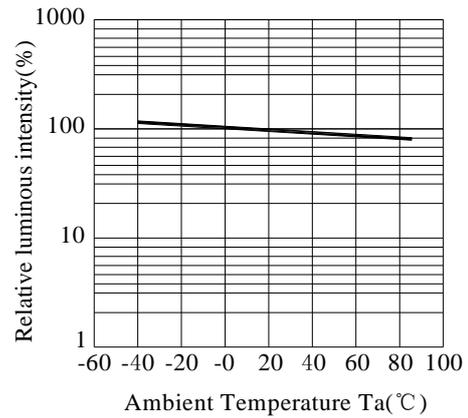


Fig.5 Luminous Intensity vs. Ambient Temperature

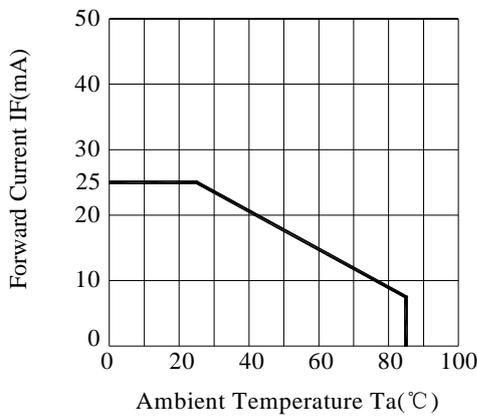


Fig.6 Forward Current Derating Curve

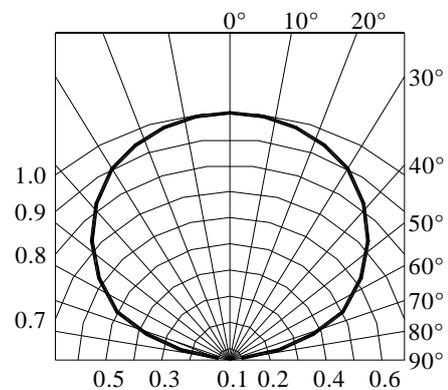


Fig.7 Relative Intensity vs. Angle



SURFACE MOUNT DEVICE LED

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● Label Explanation



ITEM CODE:PARA LIGHT

PART NO: L-C195JRLBCT

IV --- Luminous Intensity Code

LOT NO:	<u>EM</u>	<u>S</u>	<u>L</u>	<u>12</u>	<u>09</u>	<u>0110</u>
	A	B	C	D	E	F

A---EM: Emos Code

B---S:SMD

C---Local

D---Year

E---Month

F---SPEC.

PACKING QUANTITY OF BAG :

3000pcs for 150、170、110、155、115 series

4000pcs for 191 series

5000pcs for 192 series

DATE CODE:	<u>2012</u>	<u>09</u>	<u>10</u>
	G	H	I

G--- Year

H--- Month

I --- Day

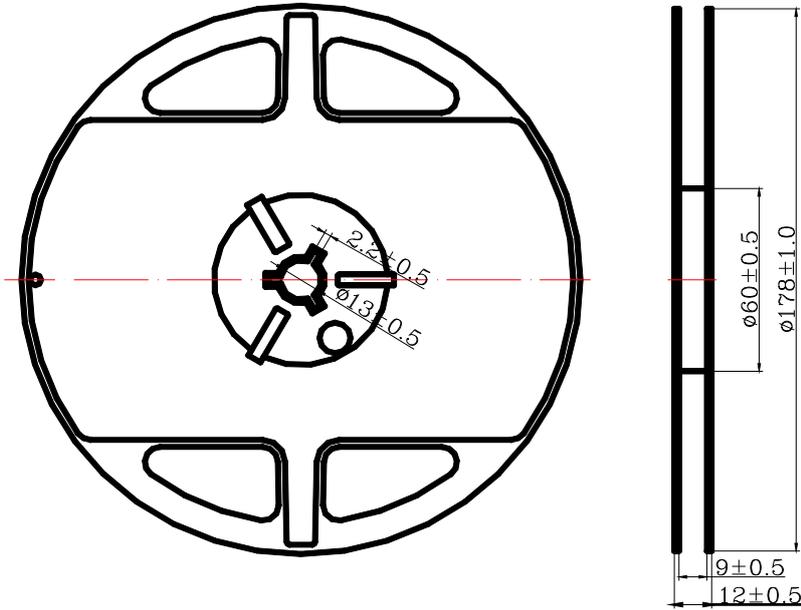


SURFACE MOUNT DEVICE LED

Part No.: L-C195JRLBCT

REV: A / 4

● Reel Dimensions



Notes:

1. Taping Quantity: 3000pcs
2. The tolerances unless mentioned is $\pm 0.1\text{mm}$, Angle $\pm 0.5^\circ$, Unit: mm.

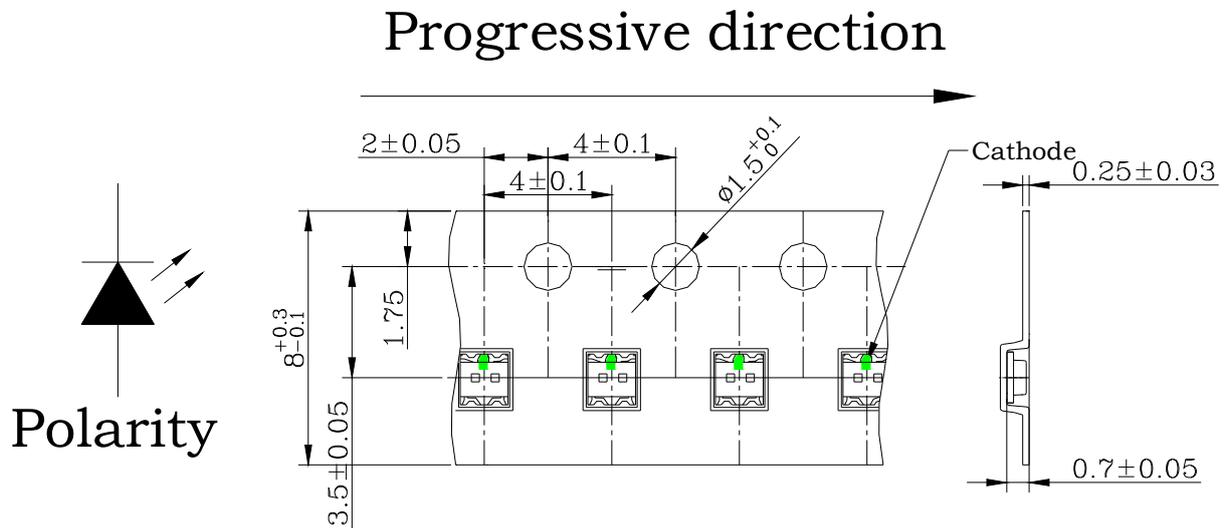


SURFACE MOUNT DEVICE LED

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● Package Dimensions Of Tape And Reel

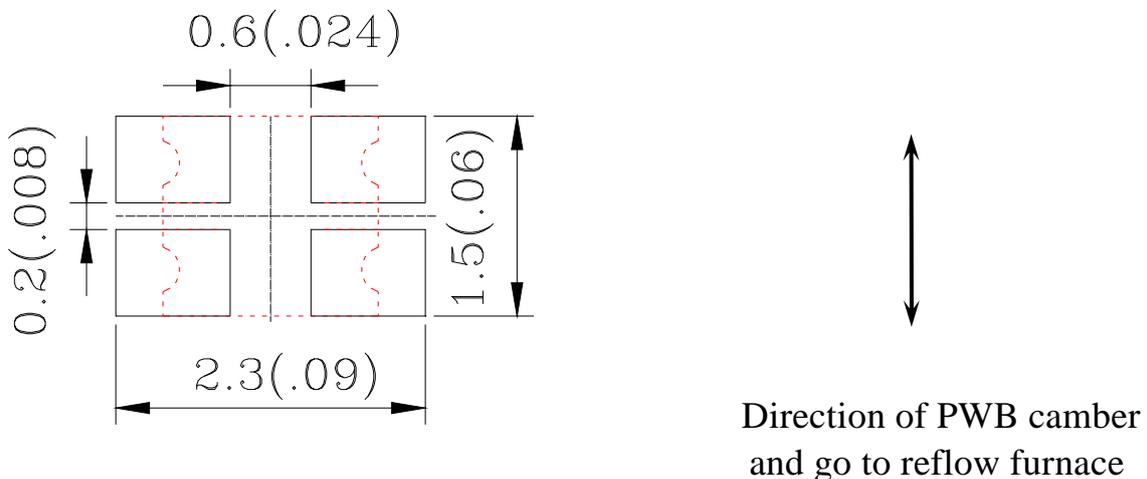


Notes: All dimensions are in millimeters.

● Cleaning

- * If cleaning is required , use the following solutions for less than 1 minute and less than 40°C.
- * Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- * Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

● Suggest Soldering Pad Dimensions



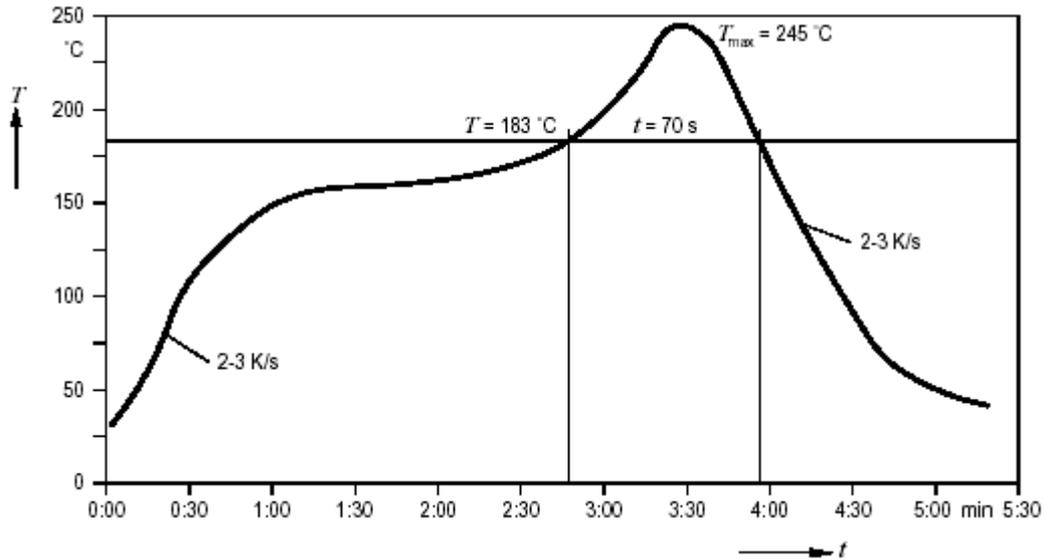


SURFACE MOUNT DEVICE LED

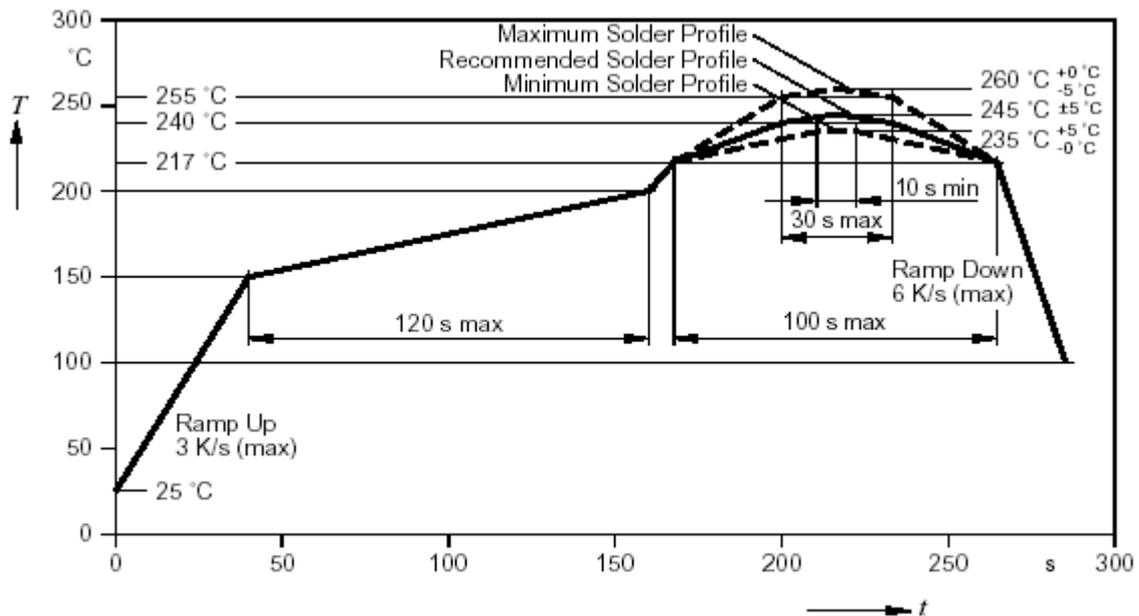
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● Suggest Sn/Pb IR Reflow Soldering Profile Condition:



● Suggest Pb-Free IR Reflow Soldering Profile Condition:





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● Bin Code List

Luminous Intensity (IV), Unit: mcd@20mA					
Red (a chip)			Blue (b chip)		
Bin Code	Min	Max	Bin Code	Min	Max
N	28	45	Q	71	112
P	45	71	R	112	180
Q	71	112	S	180	280

Tolerance of each bin are $\pm 15\%$

Forward Voltage(VF), Unit:V@20mA		
Blue (b chip)		
Bin Code	Min	Max
K8	2.8	2.95
K9	2.95	3.10
K10	3.10	3.25
K11	3.25	3.40

Tolerance of each bin are ± 0.1 Volt

Dominant Wavelength (Hue), Unit: nm@20mA		
Blue (b chip)		
Bin Code	Min	Max
AC	465	470
AD	470	475

Tolerance of each bin are ± 1 nm

CAUTIONS

1.Application Limitation:

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application). Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2.Storage:

Do not open moisture proof bag before the products are ready to use.

Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60 \pm 5°C for 24 hours



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3. Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering condition.

Reflow Soldering:

Pre-heat 120~150°C, 120sec. MAX., Peak temperature : 240°C Max. Soldering time: 10 sec Max.

Soldering Iron: (Not recommended)

Temperature 300°C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.

Wave soldering:

Pre-heat 100°C Max, Pre-heat time 60 sec. Max, Solder wave 260°C Max, Soldering time 5 sec. Max. performed consecutively cooling process is required between 1st and 2nd soldering processes.

4. Lead-Free Soldering

For Reflow Soldering:

- 1、Pre-Heat Temp:150-180°C,120sec.Max.
- 2、Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3、Peak Temperature:260°C、5sec.
- 4、Reflow Repetition:2 Times Max.
- 5、Suggest Solder Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu

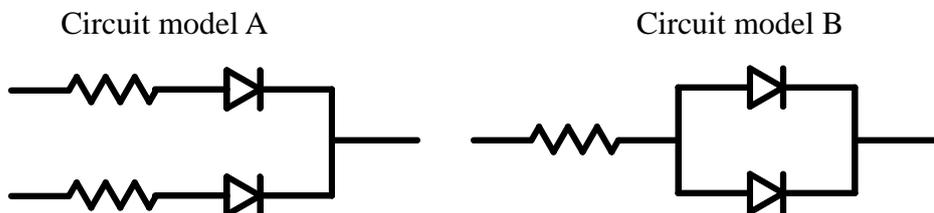
For Soldering Iron (Not Recommended):

- 1、Iron Tip Temp:350°C Max.
- 2、Soldering Iron:30w Max.
- 3、Soldering Time:3 Sec. Max. One Time.

For Dip Soldering:

- 1、Pre-Heat Temp:150°C Max. 120 Sec. Max.
- 2、Bath Temp:265°C Max.
- 3、Dip Time:5 Sec. Max.

5. Drive Method



(A)Recommended circuit.

(B)The difference of brightness between LED`s could be found due to the Vf-If characteristics of LED.